
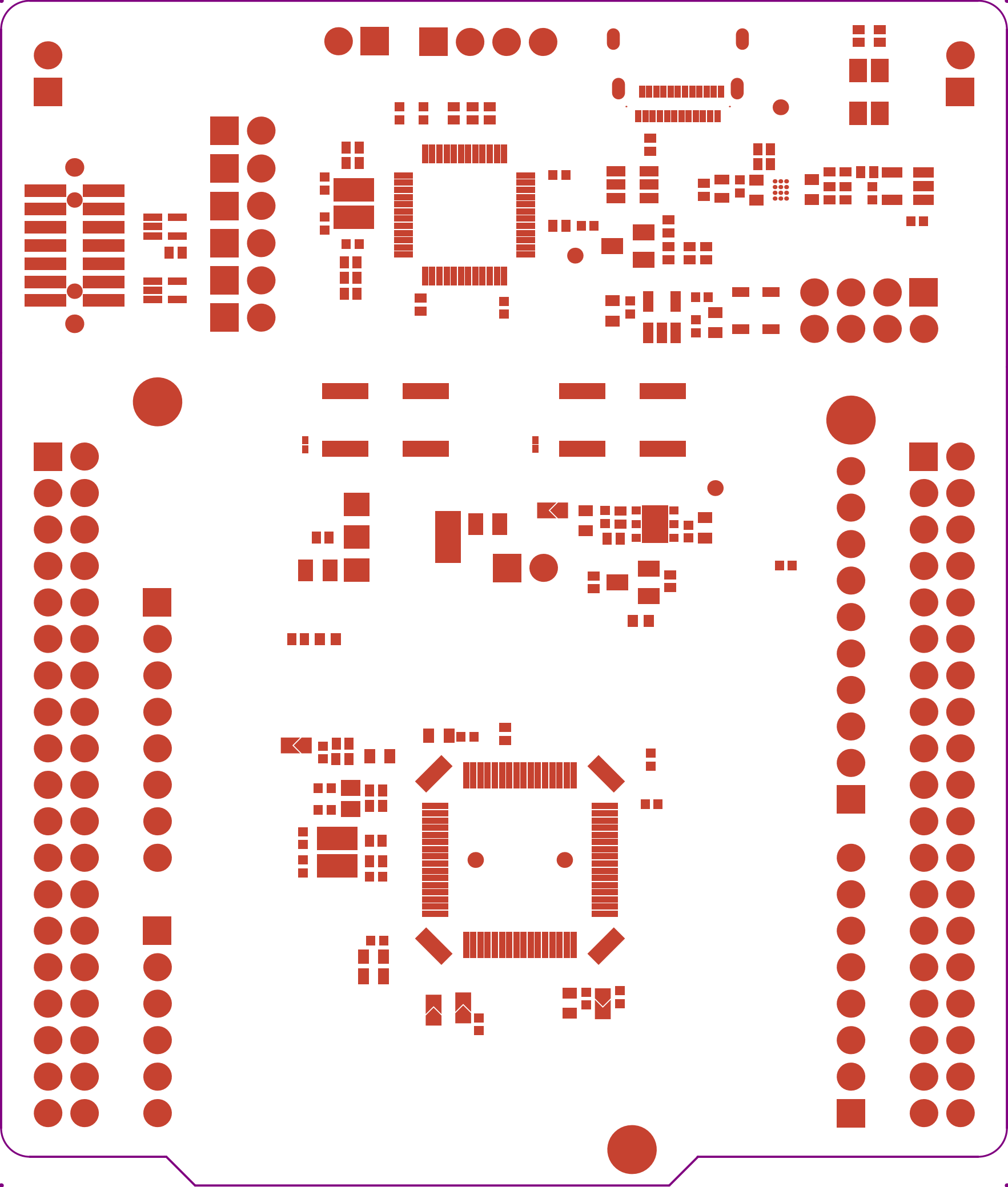

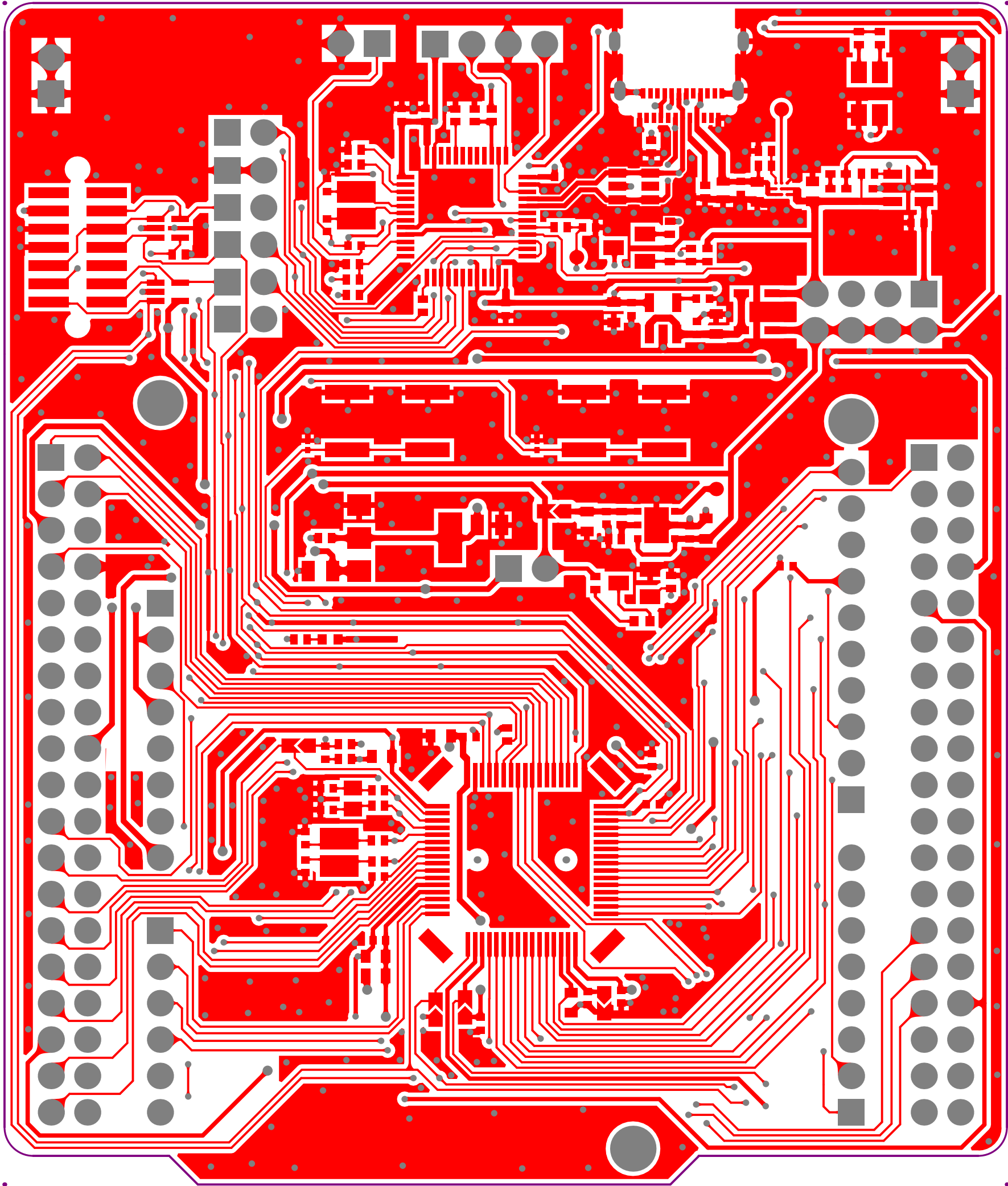



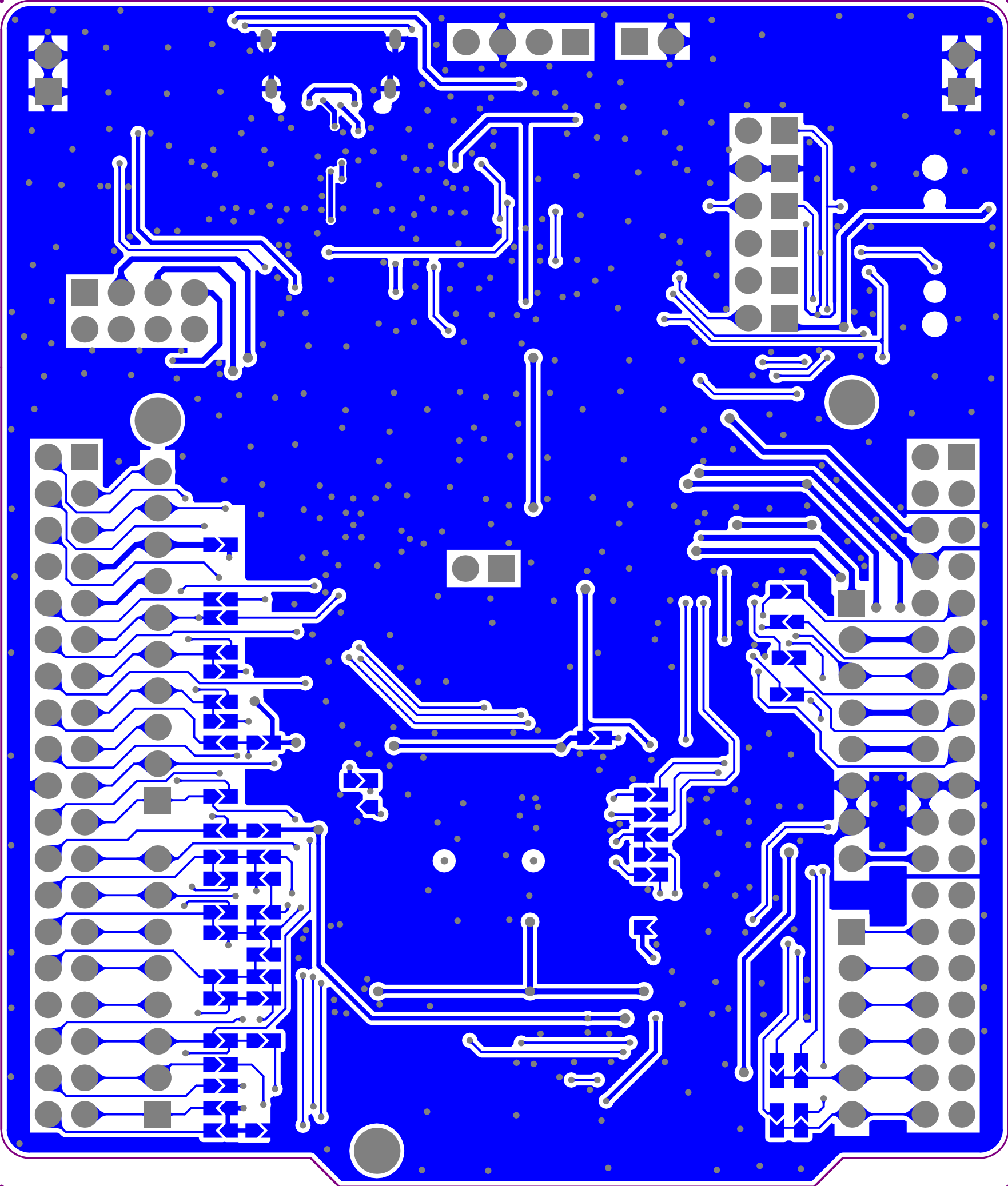
Project: NUCLEO		
Layer: Top Overlay	Gerber: .GTO	
Variant: U083RC	Ref: MB1932	
Date: 28-ARP-2023	Rev: B	



Project: NUCLEO		
Layer: Top Solder	Gerber: .GTS	
Variant: U083RC	Ref: MB1932	
Date: 28-ARP-2023	Rev: B	



Project: NUCLEO		
Layer: Top Layer	Gerber: .GTL	
Variant: U083RC	Ref: MB1932	
Date: 28-ARP-2023	Rev: B	



Project: NUCLEO

Layer: Bottom Layer

Variant: U083RC

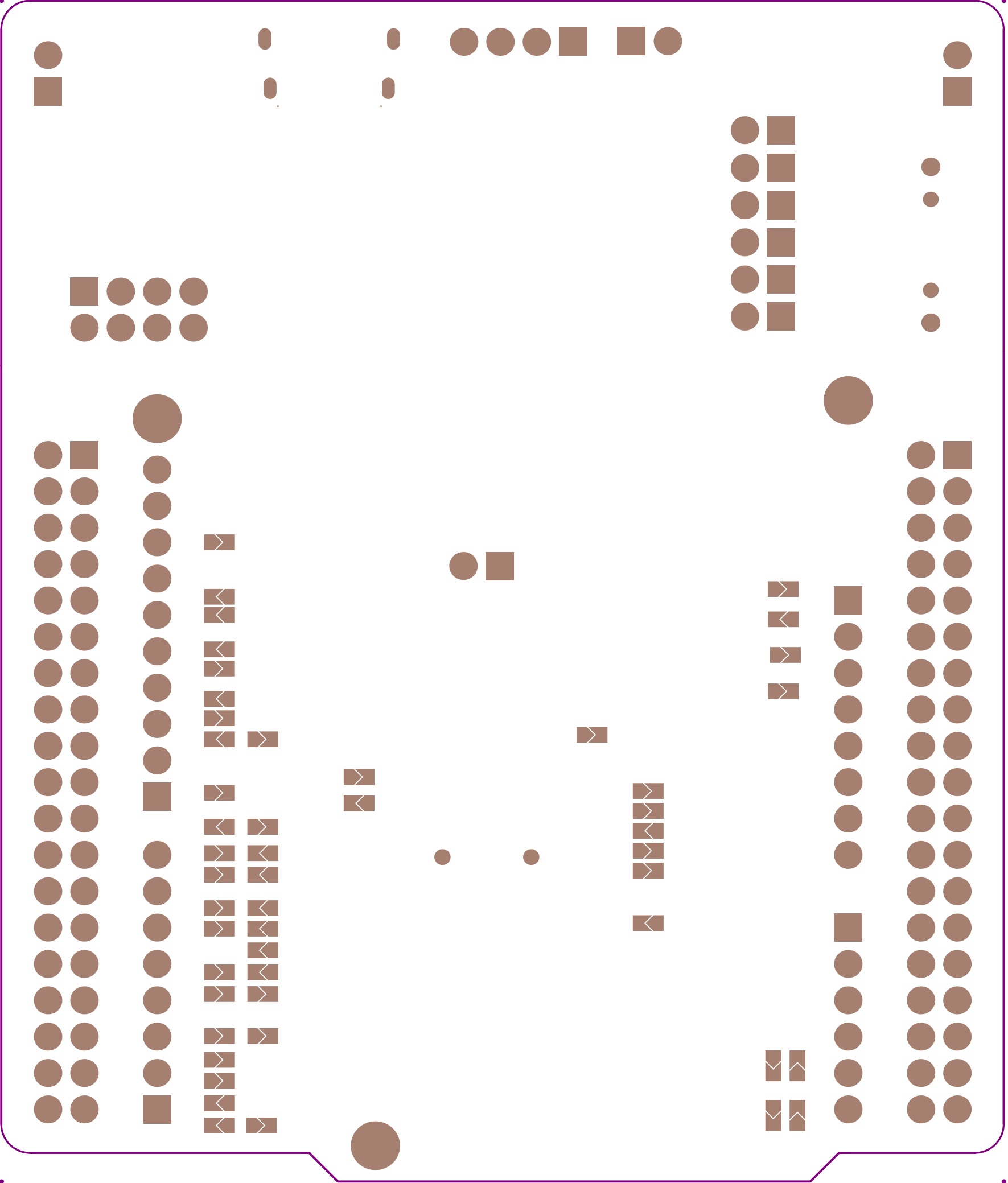
Date: 28-ARP-2023


Gerber:.GBL

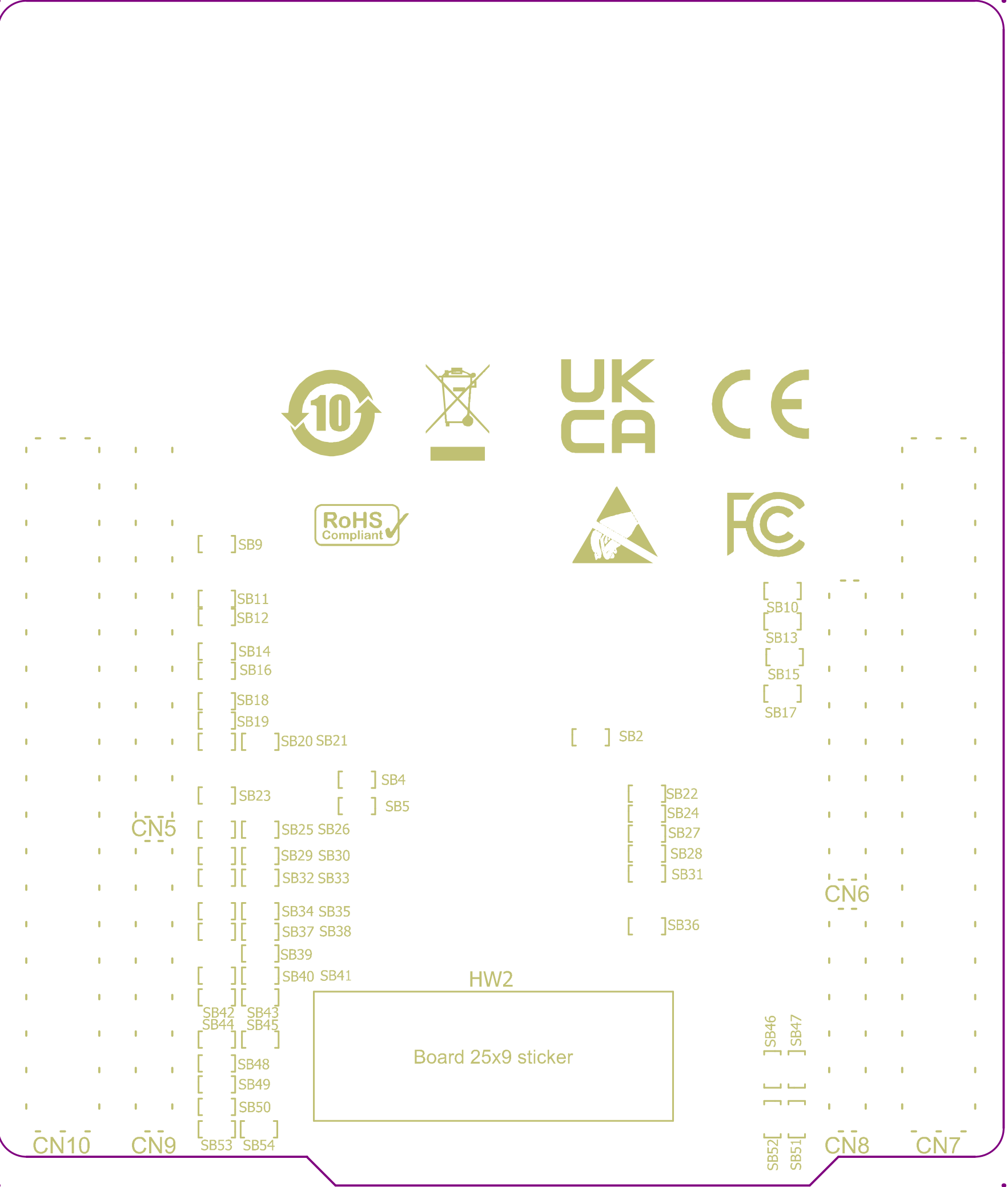
Ref: MB1932


Rev: B





Project: NUCLEO		
Layer: Bottom Solder	Gerber:.GBS	
Variant: U083RC	Ref: MB1932	
Date: 28-ARP-2023	Rev: B	



Project: NUCLEO		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: U083RC	Ref: MB1932	
Date: 28-ARP-2023	Rev: B	

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☐ BLUE

☐ BLACK

☐ WHITE

☐ YELLOW

☐ BLACK

☒ Blue ink PANTONE 2955

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL :

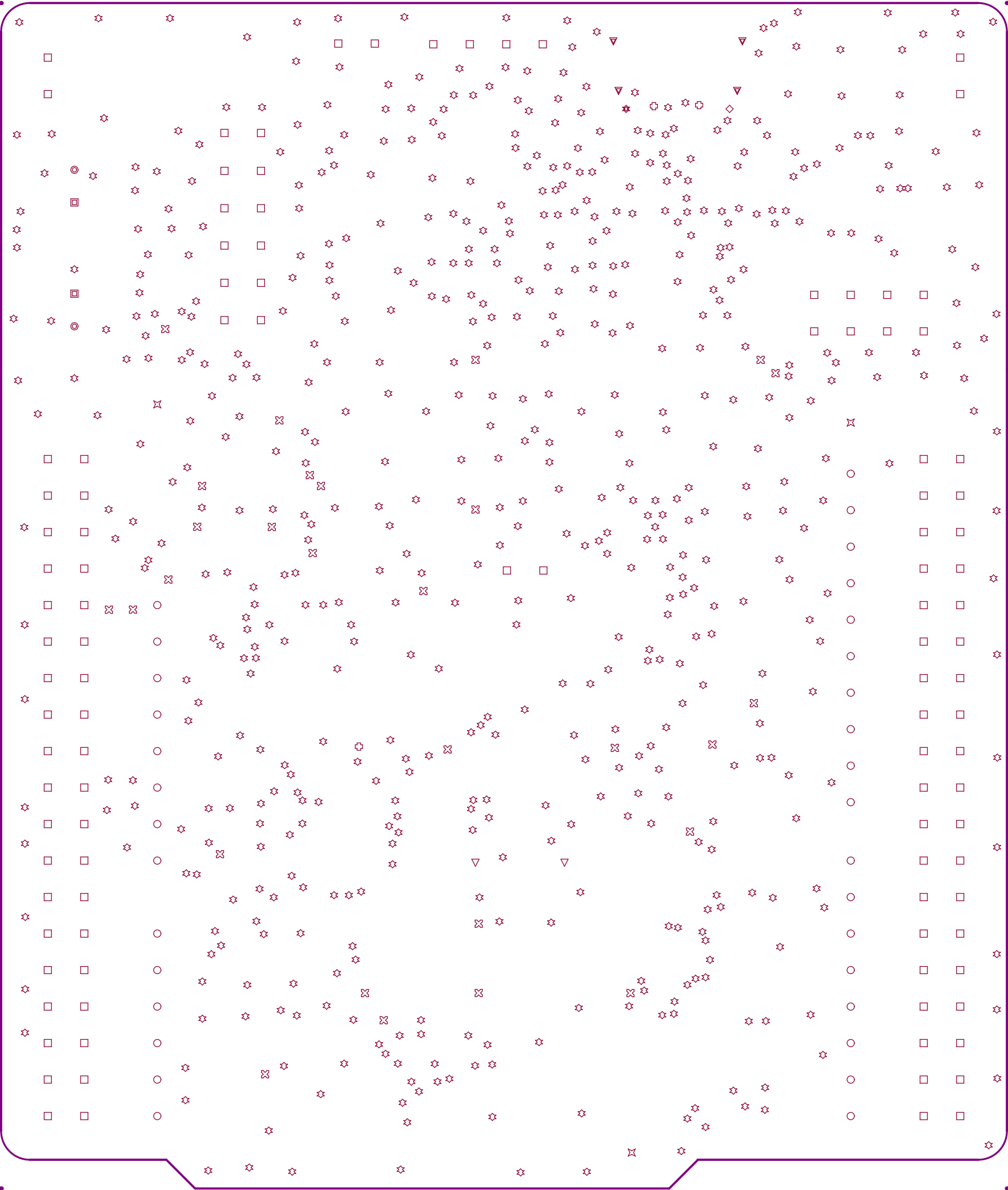
☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

IMPEDANCE TABLE USB HS STLINK

LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	0.35	0.127	n/a	90 ohm	+/- 15%



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer		0.035mm		
	Dielectric 1	FR-4	1.473mm	4.2	
2	Bottom Layer		0.035mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.152mm
GAPS : 0.127mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Hole Length	Routed Path Length
◇	1	25.59mil (0.65mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
✳	1	25.59mil (0.65mm)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	37.40mil (0.95mm)	11.81mil (0.30mm)
▣	2	38.19mil (0.97mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
▽	2	39.37mil (1.00mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
◎	2	46.85mil (1.19mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
⊕	3	11.81mil (0.30mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	-	-
✕	3	125.98mil (3.20mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
▽	4	19.69mil (0.50mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	43.31mil (1.10mm)	23.62mil (0.60mm)
✕	28	15.75mil (0.40mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	-	-
○	32	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
□	108	39.37mil (1.00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-	-
✳	618	9.84mil (0.25mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	-	-
	804 Total								

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: NUCLEO

Layer: Drill Drawing

Gerber: .DRL

Variant: U083RC

Ref: MB1932

Date: 28-ARP-2023

Rev: B

